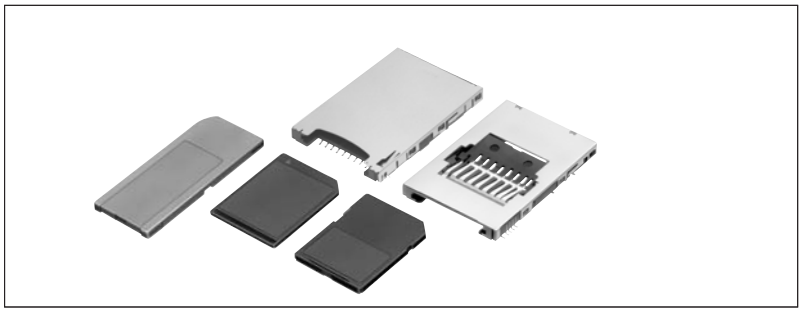
Combine Type Connector (for SD Memory Card, MultiMediaCard™, Memory Stick™)

SCDB Series

RoHS compliant

Push-push type featuring contact protection function with less impact to media cards.



Features

- Applicable to three memory card standards - SD Memory Card, Multi Media Card™ and Memory Stick™.
- Push-push ejection mechanism applied in both card types.
- Contact point protection to minimize card damage during insertion and ejection.
- Same insertion and ejection position applied for both cards.

Applications

- For desktop PCs, notebook PCs and personal digital assistants
- For home audio equipment (TVs and set top boxes)
- For audio systems
- For digital camcorders
- For digital still cameras
- For headphone players

Typical Specifications

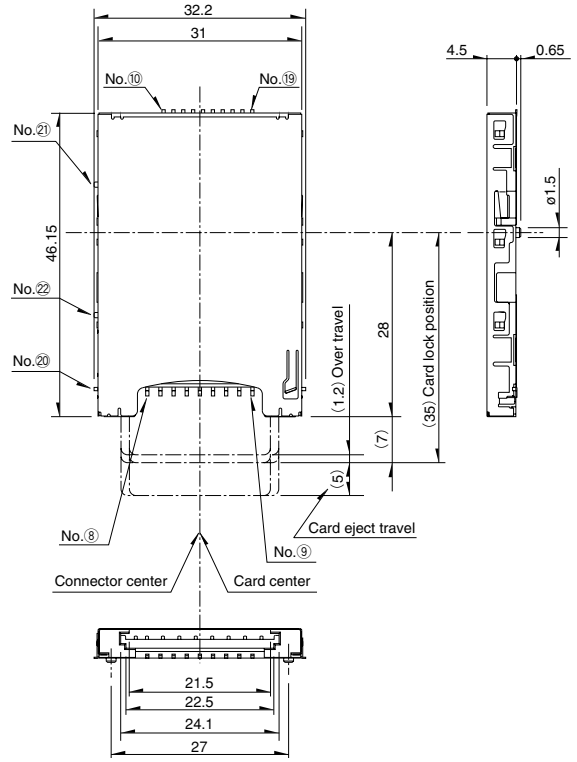
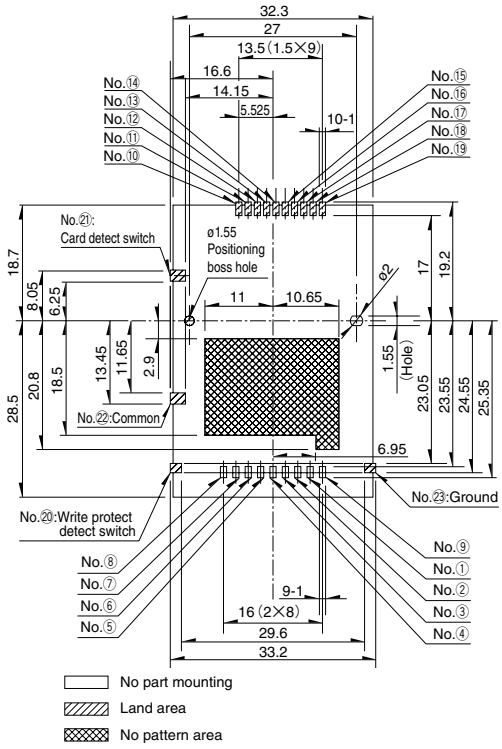
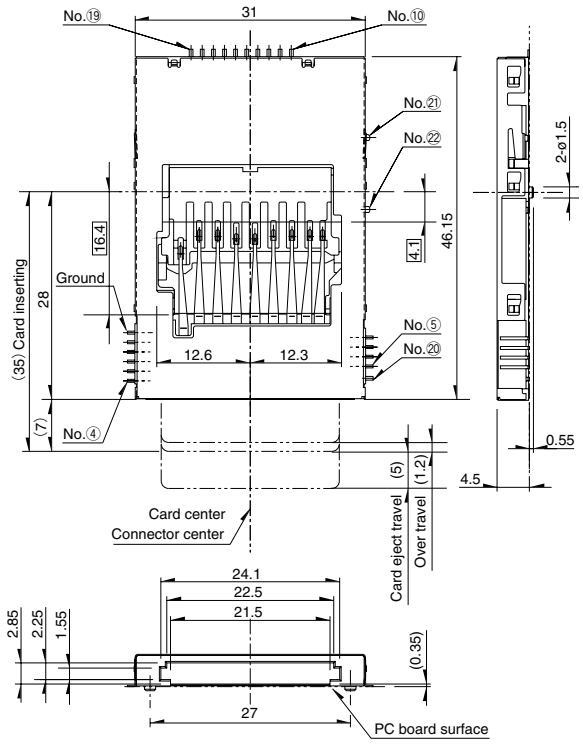
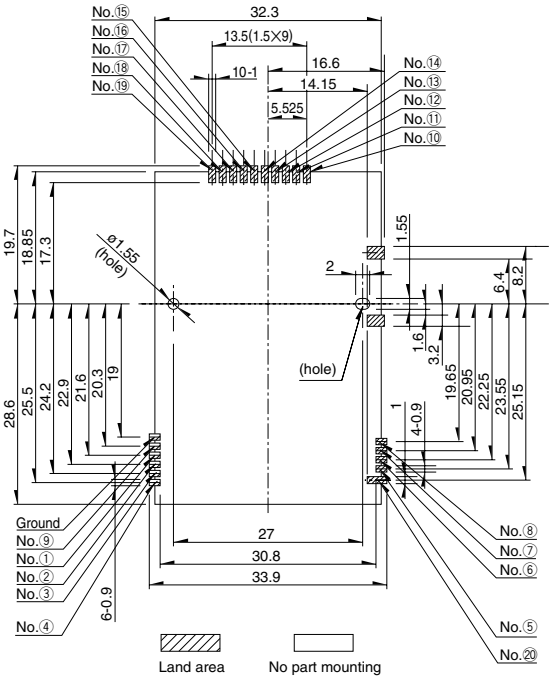
Items			Specifications
Structure	Applicable media		SD Memory Card, MultiMediaCard™, Memory Stick™
	Mounting type		Surface mounting type
	Mounting style		Standard mount/Reverse mount
	Media ejection structure		Push-push type
Performance	Operating temperature range		−25℃ to +60℃
	Voltage proof		500V AC 1minute
	Insulation resistance (Initial)		1,000MΩ min.
	Contact resistance (Initial)	Connector contacts	100mΩ max.
		Detection switch	500mΩ max.
	Insertion and removal cycle		10,000cycles (SD Memory Card) 12,000cycles (Memory Stick™)

Product Line

Media ejection structure	Mounting system	Feature	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	With boss	0	Tray	SCDB1C0105	1
	Reverse mount				SCDB2A0200	2

Dimensions

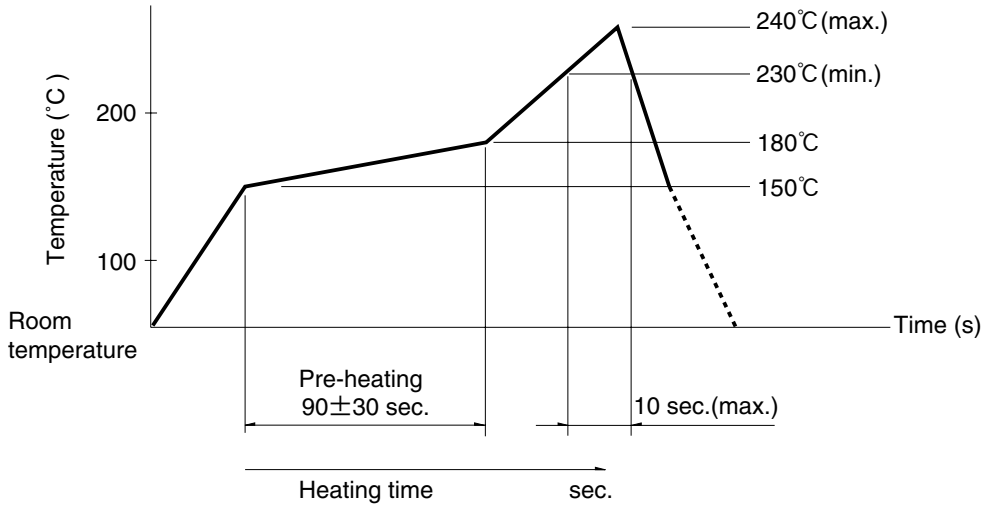
Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
1	**Standard mount** 	
2	**Reverse mount** 	

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.